



Case No. : JENSEN-015X
Patent Appln.
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicants: Aaron U. Levy et
al.
Serial No.: 09/633,297
Filed: August 3, 2000
For: MODULAR PANEL STACKING
PROCESS

Group No.: 2812
Examiner: Jones, J.

A M E N D M E N T

ASSISTANT COMMISSIONER FOR PATENTS
WASHINGTON D C 20231

Dear Sir/Madam:

In response to the initial Office Action rendered by the U.S. Patent and Trademark Office in relation to the above-identified reissue application, please amend the application as follows:

In the Claims:

7. (Amended) A chip stack comprising:

at least two packaged chips, each of the packaged chips having opposite sides and a multiplicity of leads extending from each of the opposite sides thereof; and

at least one frame extending along at least each of the opposite sides of the packaged chips and comprising: